SEMTECH

PROTECTION PRODUCTS

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20µs)	P _{pk}	100	Watts
Maximum Peak Pulse Current (tp = 8/20µs)	l _{pp}	10	Amps
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{esd}	+/- 30 +/- 30	kV
Operating Temperature	T,	-40 to +85	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}				3.3	V
Punch-Through Voltage	V _{PT}	Ι _{ΡΤ} = 2μΑ	3.5	3.8	4.3	V
Snap-Back Voltage	V _{SB}	I _{sb} = 50mA	2.8			V
Reverse Leakage Current	I _R	V _{RWM} = 3.3V		0.01	0.05	μA
Clamping Voltage	V _c	I _{PP} = 1A, tp = 8/20μs			5.6	V
Clamping Voltage	V _c	I _{pp} = 10A, tp = 8/20μs			11	V
Variation in capacitance with reverse bias ¹		Pins 1, 8 to 2, 7 and pins 3, 6 to 4, 5 VR = 0 to 2.5V f = 1MHz Pins 1, 8 to 2, 7 and pins 3, 6 to 4, 5 VR = 2.5V, f = 1MHz		1.3		pF
Junction Capacitance	C _j	I/O pin to Gnd V _R = OV, f = 1MHz		4.5	6	pF

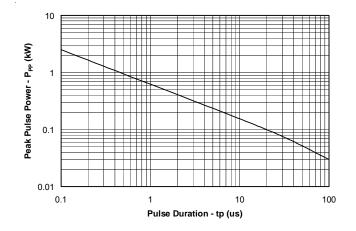
Notes:

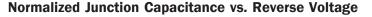
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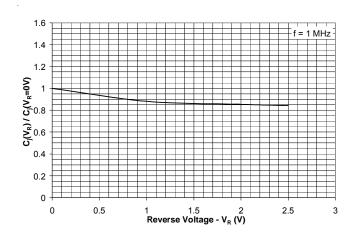
1) This parameter guaranteed by design and characterization and is not production tested

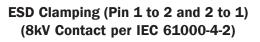


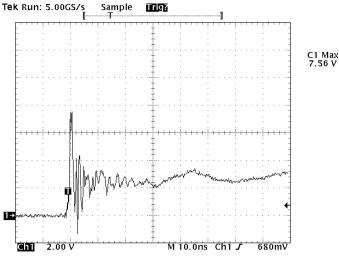
Non-Repetitive Peak Pulse Power vs. Pulse Time





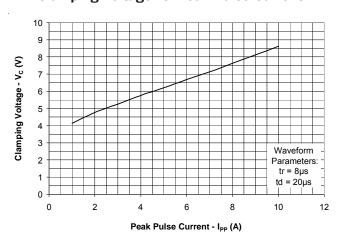




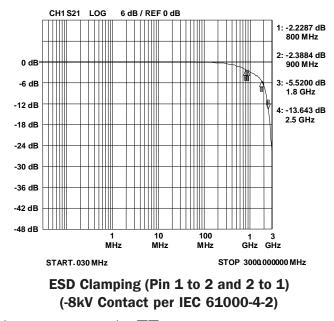


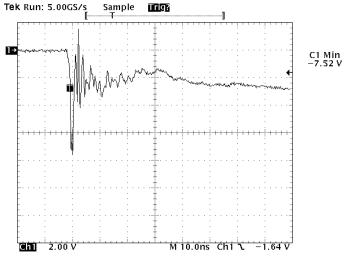
Note: Data is taken with a 10x attenuator

Clamping Voltage vs. Peak Pulse Current



Typical Insertion Loss (S21)





Note: Data is taken with a 10x attenuator

Downloaded from Arrow.com.



PROTECTION PRODUCTS

Applications Information

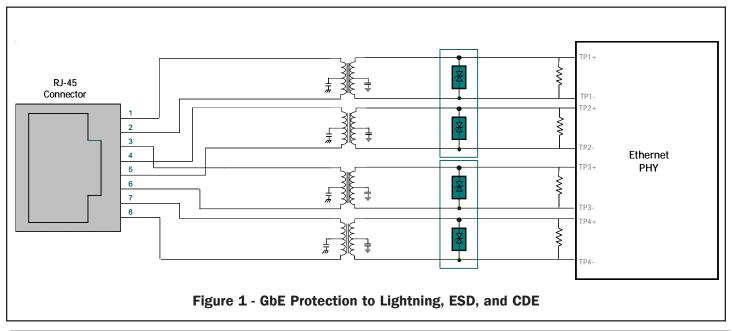
Gigabit Ethernet Protection Solutions

Ethernet systems with connections external to the building are subject to high-level transient threats. This type of equipment may even be required to meet the surge immunity requirements of Telcordia GR-1089. Reliable protection of the Ethernet transceiver requires a device that can absorb the expected transient energy, clamp the incoming surge to a safe level, and yet remain transparent to the system under normal operation. The uClamp3312T has been designed to meet these demanding requirements. Typical IEEE 802.3 template test results for a GbE circuit with uClamp3312T are shown in Figure 2.

Transient Protection

When designing Ethernet protection, the entire system must be considered. An Ethernet port includes interface magnetics in the form of transformers and common mode chokes. Transformers and chokes can be discrete components, but integrated solutions that include the RJ-45 connector, resistors, capacitors, and protection are also available. In either case, the transformer will provide a high level of common mode isolation to external voltages, but no protection for metallic (line-to-line) surges. During a metallic transient event, current will flow into one line, through the transformer and back to the source. As the current flows, it charges the windings of the transformer on the line side. Once the surge is removed, the windings on the line side will stop charging and will transfer its stored energy to the IC side where the PHY IC is located. The magnitude and duration of the surge is attenuated by the inductance of the magnetics. The amount of attenuation will vary by vendor and configuration of the magnetics. It is this transferred energy that must be clamped by the protection circuitry.

A typical protection scheme which utilizes the uClamp3312T is shown in Figure 1. One device is placed across two line pairs and is located on the PHY side of the transformer as close to the magnetics as possible. This is done to minimize parasitic inductance and improve clamping performance. In this design, the isolation voltage of the transformer is relied upon to suppress common mode lightning surges. High voltage capacitors and resistors are commonly utilized from the center tap to ground to aid in transient protection. Metallic surges will be transferred in some form to the PHY side and clamped by the uClamp3312T. The uClamp3312T will turn on when the voltage across it exceeds the punch-through voltage of the device. Low voltage turn on is important since many PHY chips have integrated ESD protection structures. These structures are for protection of the device during manufacture and are not designed to handle large amounts of energy. Should they turn on before the external protection, they can be damaged resulting in failure of the PHY chip.







Point A



Point C



Point F



Point B

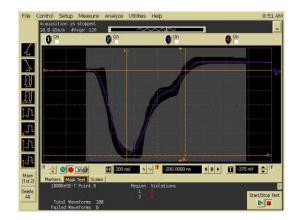








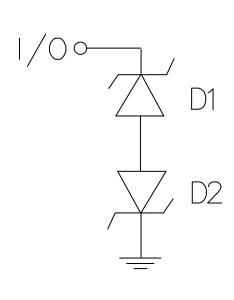


Figure 2 - Typical IEEE 802.3 Template Test Results (With uClamp3312T)



PROTECTION PRODUCTS

Applications Information - Spice Model



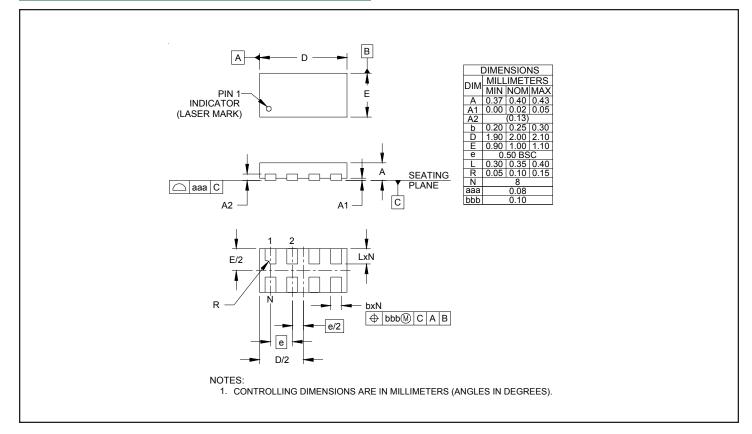
Spice Model

uClamp3312T Spice Parameters						
Parameter	Unit	D1 (TVS)	D2 (TVS)			
IS	Amp	1E-20	1E-20			
BV	Volt	2.8	2.8			
٧J	Volt	0.7	0.7			
RS	Ohm	0.2	0.2			
IBV	Amp	1E-3	1E-3			
CJO	Farad	10E-12	1E-12			
TT	sec	2.541E-9	2.541E-9			
М		0.05	0.05			
N		1.1	1.1			
EG	eV	1.11	1.11			

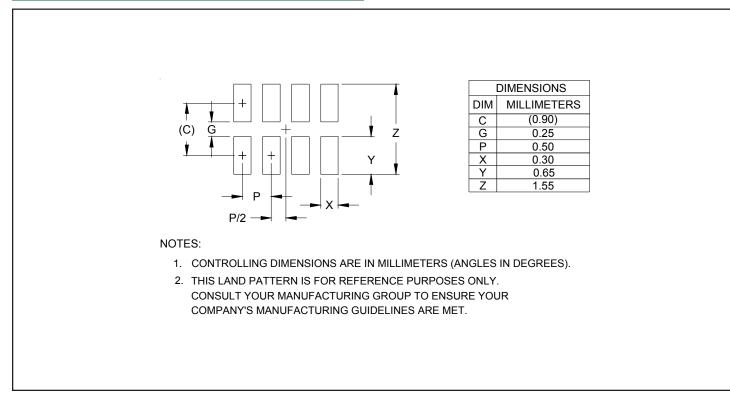


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Outline Drawing - SLP2010N8T



Land Pattern - SLP2010N8T



EMTECH

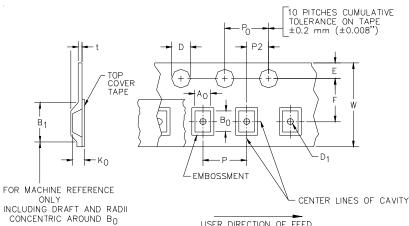
uClamp3312T

PROTECTION PRODUCTS

Marking Code

YYWW = Date Code

Tape and Reel Specification



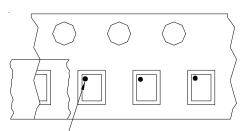
USER DIRECTION OF FEED

Ordering Information

Part Number	Working	Qty per	Reel	
	Voltage	Reel	Size	
uClamp3312T.TCT	3.3V	3,000	7 Inch	

Notes:

1) MicroClamp, uClamp and µClamp are marks of Semtech Corporation



Pin 1 Location

User Direction of feed

Device Orientation in Tape

mm (.016)

(.079±.002)

W

8.0 mm

+ 0.3 mm

- 0.1 mm

 $(.312\pm.012)$

	A0	B0		КО					
1.21 +/	-0.05 mm	m 2.21 +/-0.05	mm	0.66 +/-0.05 mm	ı				
Tape Width	B, (Max)	ax) D	D1	E	F	Ρ	PO	P2	Т
8 mm	4.2 mm		0.4 mm ±0.25	mm	3.5±0.05 mm	4.0±0.10 mm	4.0±0.1 mm (157±00-	2.0±0.05 mm	0.254±0.0

(.069±.004)

(.031)

(.138±.002)

Contact Information

(.165)

(0.59 +.005

- .000)

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